ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22142X
Issue Date: 7 March 2018

Title of Change:	Final Test Capacity expansion for NCP81078MNTBG and NCP81080MNTBG-- addition of final test locations to Seremban, Malaysia and Tarlac, Philippines
Proposed first ship date:	14 June 2018 *or earlier upon customer approval.*
Contact information:	Contact your local ON Semiconductor Sales Office or <Ryan.Zhou@onsemi.com>
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Ryan.Zhou@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Customer may receive the parts from any of ON Semiconductor's facilities (Carmona, Philippines; Tarlac, Philippines; Seremban, Malaysia) from April 14, 2018 once the PCN expires or earlier depending on customer's approval. Parts tested in ON Semiconductor facilities can be identified through product packaging and labelling which follow ON Semiconductor standard.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☒ Test Change ☐ Other ______________

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ______________________

Sites Affected:	ON Semiconductor Sites: ON Seremban, Malaysia ON Tarlac City, Philippines	External Foundry/Subcon Sites: None

Description and Purpose:

ON Semiconductor has completed the qualification of two additional production test sites as shown in the following table. The purpose is to only expand test capacity and support expected increased volume. There is no change to the design, package, assembly, test coverage/flow, or datasheet.

Change Item:	Before Change Description	After Change Description
Location	ON Semiconductor, Carmona, Philippines.	After the change, Final Test will be done in three locations, Seremban, Malaysia, Carmona and Tarlac, Philippines
Test equipment	Eagle ETS364, Octal site test with NX32 test board and handler.	Eagle ETS364, Octal site test with NX32 test board and handler. Eagle ETS88, Dual site test with NX16 test board and handler

Qualification Plan:

Completed the qualification requirement per plan. The scope was to perform electrical test on the new test equipment and confirm comparable results achieved to the existing test equipment:

NCP81078MNTBG				
Qualification Items/Steps	**Quality Characteristic / Response to be Monitored** (Input, in-process, Output)	**Test /Condition**	**Sample Size**	**Accept Criteria / Result**
Probe, Assy, Test *(Yield, GDPW, Correlation, etc.)*	Test fresh lots in ETS88	Per existing spec	100%	Achieve comparable yield / Passed
Key Parameter Electrical Distribution Comparison (Before & After & Post Stress)	10pcs correlation between ETS88 vs. ETS364	Per existing spec	100%	10/10 must correlate between 2 test platforms / Passed
Reject Bin Analysis	Rejects verification in both test platforms (ETS88 vs. ETS364)	Per existing spec	100%	Rejects must correlate between 2 test platforms / Passed
Electrical QA	Retest ETS88 FT Bin 1 in QA mode	Per existing spec	100%	100% yield / Passed

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NCP81078MNTBG	NCP81078MNTBG
NCP81080MNTBG	